

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>XIANG LI</td> <td>12/18/2013</td> </tr> <tr> <td>JIANLE CHEN</td> <td>12/18/2013</td> </tr> <tr> <td>MARTA KARCEWICZ</td> <td>12/18/2013</td> </tr> <tr> <td>VADIM SEREGIN</td> <td>12/18/2013</td> </tr> <tr> <td>WEI PU</td> <td>12/18/2013</td> </tr> <tr> <td>KRISHNAKANTH RAPAKA</td> <td>12/18/2013</td> </tr> <tr> <td>LIWEI GUO</td> <td>12/18/2013</td> </tr> </tbody> </table>		Name	Execution Date	XIANG LI	12/18/2013	JIANLE CHEN	12/18/2013	MARTA KARCEWICZ	12/18/2013	VADIM SEREGIN	12/18/2013	WEI PU	12/18/2013	KRISHNAKANTH RAPAKA	12/18/2013	LIWEI GUO	12/18/2013
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<table border="1"> <tr> <td>Name:</td> <td>QUALCOMM INCORPORATED</td> </tr> <tr> <td>Street Address:</td> <td>5775 MOREHOUSE DRIVE</td> </tr> <tr> <td>City:</td> <td>SAN DIEGO</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>92121-1714</td> </tr> </table>		Name:	QUALCOMM INCORPORATED	Street Address:	5775 MOREHOUSE DRIVE	City:	SAN DIEGO	State/Country:	CALIFORNIA	Postal Code:	92121-1714						
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Application Number:	14137101																
CORRESPONDENCE DATA																	
Fax Number:	(949)760-9502																
Phone:	9497600404																
Email:	Daniella.Kellogg@knobbe.com																
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>																	
Correspondent Name:	KNOBBE MARTENS OLSON & BEAR LLP																
Address Line 1:	2040 MAIN STREET																
Address Line 2:	14TH FLOOR																
Address Line 4:	IRVINE, CALIFORNIA 92614																
ATTORNEY DOCKET NUMBER:	QVID.130A / 131463																
<b>PATENT</b>																	

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NAME OF SUBMITTER:	MINCHEOL KIM
Signature:	/Mincheol Kim/
Date:	12/20/2013
<b>Total Attachments: 6</b> source=QVID-130A_Assignment#page1.tif source=QVID-130A_Assignment#page2.tif source=QVID-130A_Assignment#page3.tif source=QVID-130A_Assignment#page4.tif source=QVID-130A_Assignment#page5.tif source=QVID-130A_Assignment#page6.tif	

ASSIGNMENT

WHEREAS, WE,

1. **Xiang LI**, a citizen of **China**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714** and a resident of **San Diego, CA**,
2. **Jianle CHEN**, a citizen of **China**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714** and a resident of **San Diego, CA**,
3. **Marta KARCZEWICZ**, a citizen of **U.S.A.**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714** and a resident of **San Diego, CA**,
4. **Vadim SEREGIN**, a citizen of **The Russian Federation**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714** and a resident of **San Diego, CA**,
5. **Wei PU**, a citizen of **China**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714** and a resident of **San Diego, CA**,
6. **Krishnakanth RAPAKA**, a citizen of **India**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714** and a resident of **San Diego, CA**,
7. **Liwei GUO**, a citizen of **China**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714** and a resident of **San Diego, CA**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **DEVICE AND METHOD FOR SCALABLE AND MULTIVIEW/3D CODING OF VIDEO INFORMATION** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/137,101 filed December 20, 2013,

Qualcomm Reference No. 131463, and all provisional applications relating thereto, together with U.S. Provisional Application No. 61/758,723, filed January 30, 2013, Qualcomm Reference No. 131463P1, U.S. Provisional Application No. 61/790,200, filed March 15, 2013, Qualcomm Reference No. 131463P2, U.S. Provisional Application No. 61/747,028, filed December 28, 2012, Qualcomm Reference No. 131079P1, U.S. Provisional Application No. 61/747,113, filed December 28, 2012, Qualcomm Reference No. 131123P1, U.S. Provisional Application No. 61/748,245, filed January 2, 2013, Qualcomm Reference No. 131123P2, U.S. Provisional Application No. 61/751,794, filed January 11, 2013, Qualcomm Reference No. 131267P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

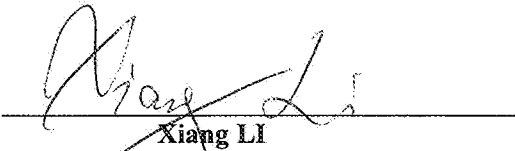
AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;


AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;


AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us


respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

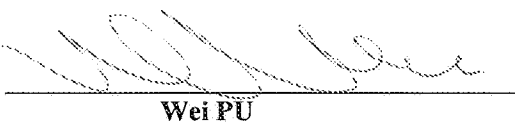
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, on 12/18/2013   
LOCATION DATE Xiang LI


Done at San Diego, on 12/18/2013   
LOCATION DATE Jianle CHEN

Done at San Diego, on 12/18/13   
LOCATION DATE Marta KARCZEWICZ

Done at San Diego, CA, on 12/18/2013   
LOCATION DATE Vadim SEREGIN

Done at San Diego, CA, on 12/18/2013   
LOCATION DATE Wei PU

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Krishnakanth RAPAKA

Done at San Diego, on 12/18/2013   
LOCATION DATE Lijer GUO

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NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). \_\_\_\_\_ filed \_\_\_\_\_.

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AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us

respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Xiang LI

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Jianle CHEN

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Marta KARCZEWICZ

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Vadim SEREGIN

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Wei PU

Done at \_\_\_\_\_, on 18/12/2010  
LOCATION DATE   
Krishnakanth RAPAKA

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Liwei GUO

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